Software
Swing-Duo™

When used with our exclusive Swing Cathode™ , Swing-Duo™ (Dynamic Uniformity Optimization) software simulates the combined cathode array uniformity to produce individually optimized magnetic bar motion profiles used for setup.*

User friendly with a web-based interface, the software quickly designs coater configurations for optimal deposition uniformity.

Swing-DUO™ makes uniformity compensation for systemic issues in the form of motion profile changes.

The software prevents uniformity drift over the life of the target by creating multiple CAM tables for different target diameters

- Dwell-based simulation finds the key deposition angles and calculates the amount of time required at each angle.
- Optimizes uniformity for constant power or variable power
- Refines uniformity optimization using actual measured uniformity results
- Outputs a CAM table in angle and time format for simplified servo programming
- Indicates the amount of wasted material not deposited on the substrate as a function of the motion profiles

The software opens from the Sputtering Components website for registered users.

Visit the Sputtering Components website for a demonstration video.

Optimization Results
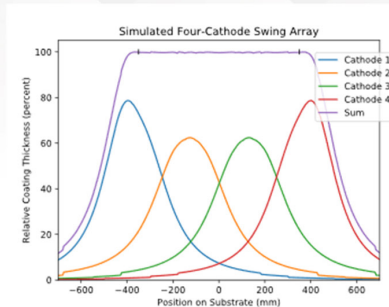
±0.26% uniformity across the substrate

13.8% cathode to cathode sputtering

31.0% sputtering wastage off the edge of the substrate (visible in profile)

5.2% sputtering wastage away from substrate (not visible in profile)

36.2% total sputtering wastage

Cathode Configuration

Simulation Output

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